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Vishay Siliconix

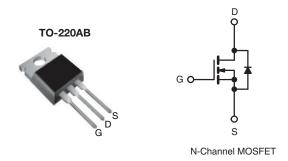
RoHS

COMPLIANT HALOGEN

**FREE** 

## **EF Series Power MOSFET with Fast Body Diode**

PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650				
R <sub>DS(on)</sub> max. at 25 °C (Ω)	V <sub>GS</sub> = 10 V 0.176				
Q <sub>g</sub> (Max.) (nC)	84				
Q <sub>gs</sub> (nC)	14				
Q <sub>gd</sub> (nC)	24				
Configuration	Single				



#### **FEATURES**

- Fast body diode MOSFET using E series technology
- Reduced t<sub>rr</sub>, Q<sub>rr</sub>, and I<sub>RRM</sub>
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Increased robustness due to low Q<sub>rr</sub>
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### **APPLICATIONS**

- Telecommunications
  - Server and telecom power supplies
- Lighting
  - High intensity discharge (HID)
  - Light emitting diodes (LEDs)
- Consumer and computing
  - ATX power supplies
- Industrial
  - Welding
  - Battery chargers
- Renewable energy
  - Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- Applications using the following topologies
  - LLC
  - Phase shifted bridge (ZVS)
  - 3-level inverter
  - AC/DC bridge

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and Halogen-free	SiHP21N60EF-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	600	V	
Gate-Source Voltage			$V_{GS}$	± 30	V	
Continuous Drain Current (T, I = 150 °C)	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I <sub>D</sub>	21	А	
Continuous Drain Current (1 <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		14		
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	53		
Linear Derating Factor				1.8	W/°C	
Single Pulse Avalanche Energy b			E <sub>AS</sub>	367	mJ	
Maximum Power Dissipation			$P_{D}$	227	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope $T_J = 125 ^{\circ}\text{C}$		dV/dt	70	V/ns		
Reverse Diode dV/dt <sup>d</sup>			20	V/IIS		
Soldering Recommendations (Peak Temperature) c for 10 s				300	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 5.1 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ , dl/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C.



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.55		

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static		•		l	•	l .	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> :	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.59	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
Cata Carrea Laglaga		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-Source Leakage	I <sub>GSS</sub>		$V_{GS} = \pm 30 \text{ V}$		-	± 1	μΑ
Zero Gate Voltage Drain Current	1	V <sub>DS</sub> =	= 480 V, V <sub>GS</sub> = 0 V	-	-	1	μА
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	500	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 11 A	-	0.153	0.176	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 30 V, I <sub>D</sub> = 11 A	-	7	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$ ,	-	2030	-	
Output Capacitance	C <sub>oss</sub>	1	$V_{DS} = 100 V,$	-	105	-	
Reverse Transfer Capacitance	$C_{rss}$		f = 1 MHz	-	5	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V 0VV 0VV 400V		-	86	-	pF
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>	V <sub>GS</sub> = 0 V	$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ V to } 480 \text{ V}$		299	-	
Total Gate Charge	Qg		V <sub>GS</sub> = 10 V I <sub>D</sub> = 11 A, V <sub>DS</sub> = 480 V		56	84	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V			14	-	nC
Gate-Drain Charge	Q <sub>gd</sub>				24	-	
Turn-On Delay Time	t <sub>d(on)</sub>	'		-	21	42	
Rise Time	t <sub>r</sub>	V <sub>DD</sub> =	$V_{DD} = 480 \text{ V}, I_{D} = 11 \text{ A}$ $R_g = 9.1 \Omega, V_{GS} = 10 \text{ V}$		31	62	
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_g = 9$			59	89	ns -
Fall Time	t <sub>f</sub>				27	54	
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz, open drain		-	0.56	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	53	- A
Diode Forward Voltage	$V_{SD}$	T <sub>J</sub> = 25 °0	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 11 A, V <sub>GS</sub> = 0 V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 11 A, dl/dt = 100 A/µs, V <sub>R</sub> = 25 V		-	135	270	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	0.76	1.52	μC
Reverse Recovery Current	I <sub>RRM</sub>			_	11	_	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

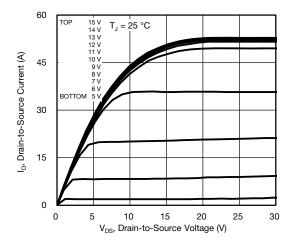


Fig. 1 - Typical Output Characteristics,  $T_J$  = 25 °C

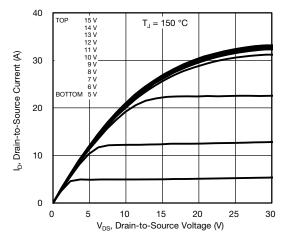


Fig. 2 - Typical Output Characteristics, T<sub>J</sub> = 150 °C

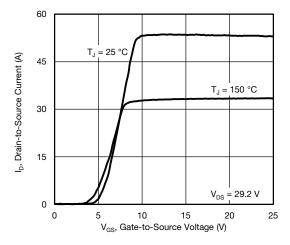


Fig. 3 - Typical Transfer Characteristics

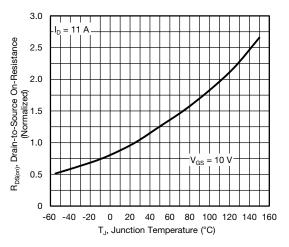


Fig. 4 - Normalized On-Resistance vs. Temperature

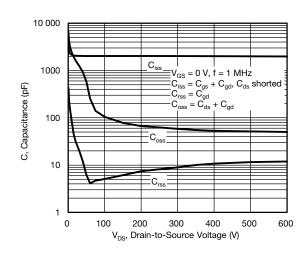


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

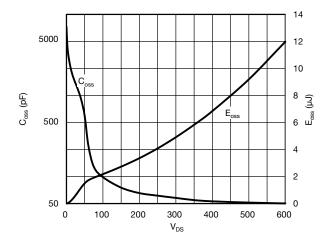


Fig. 6 - Coss and Eoss vs. VDS



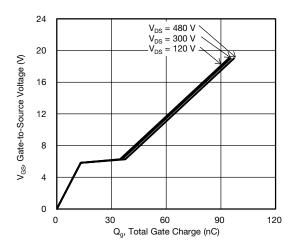


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

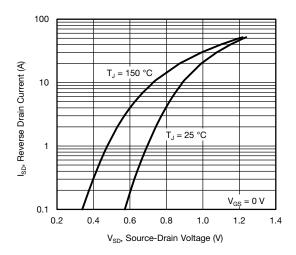


Fig. 8 - Typical Source-Drain Diode Forward Voltage

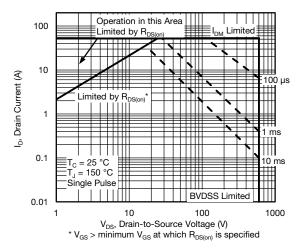


Fig. 9 - Maximum Safe Operating Area

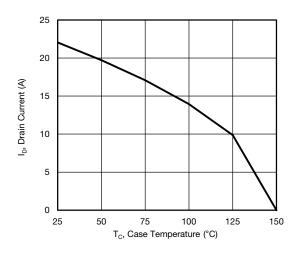


Fig. 10 - Maximum Drain Current vs. Case Temperature

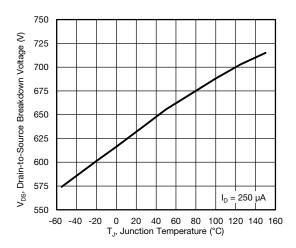
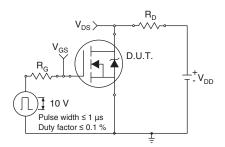


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature

Outry Cycle = 0.5

Outry Cycle =

Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case



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Fig. 13 - Switching Time Test Circuit

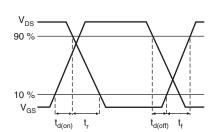


Fig. 14 - Switching Time Waveforms

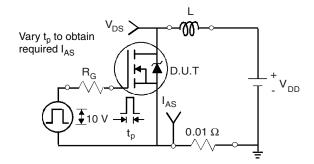


Fig. 15 - Unclamped Inductive Test Circuit

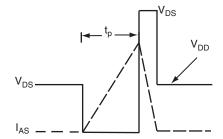


Fig. 16 - Unclamped Inductive Waveforms

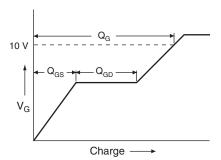


Fig. 17 - Basic Gate Charge Waveform

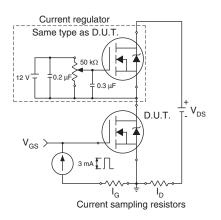
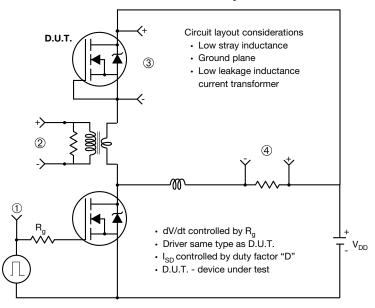


Fig. 18 - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



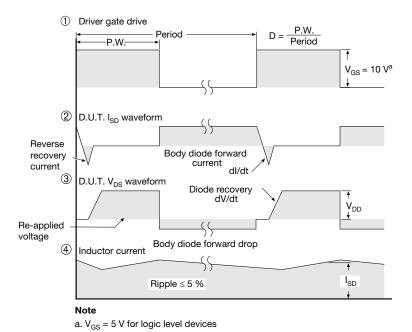


Fig. 19 - For N-Channel

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## TO-220-1



DIM	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

#### Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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